

Abstract

Wire loop, semiconductor device having same and wire bonding method

A wire loop includes a wire (3) connecting a first
5 bonding point (A) and a second bonding point (Z) therethrough,
wherein an additional wire loop (P) is formed after wire
bonding at the second bonding point (Z) without cutting the
wire (3) and the additional wire loop (P) is bonded to the
second bonding point (Z) or to the vicinity thereof while
10 part of the wire (3) is crushed.

Fig. 1A